

LVDS Interface ICs

56bit LVDS Transmitter 56:8 Serializer

**BU7988KVT**

●Description

LVDS Interface IC of ROHM "Serializer" "Deserializer" operate from 8MHz to 150MHz wide clock range, and number of bits range is from 35 to 70. Data is transmitted seven times (7X) stream and reduce cable number by 3(1/3) or less. The ROHM's LVDS has low swing mode to be able to expect further low EMI.

●Features

- Wide dot clock range : Single(112MHz)/Dual(224MHz)(NTSC, VGA, SVGA, WXGA UXGA)
- Support spread spectrum clock generator.
- Clock edge selectable.
- Support reduced swing LVDS for low EMI.
- Power down mode.
- Package TQFP100V

●Applications

Flat Plane Display

●Precaution

- This chip is not designed to protect from radioactivity.

● Block Diagram

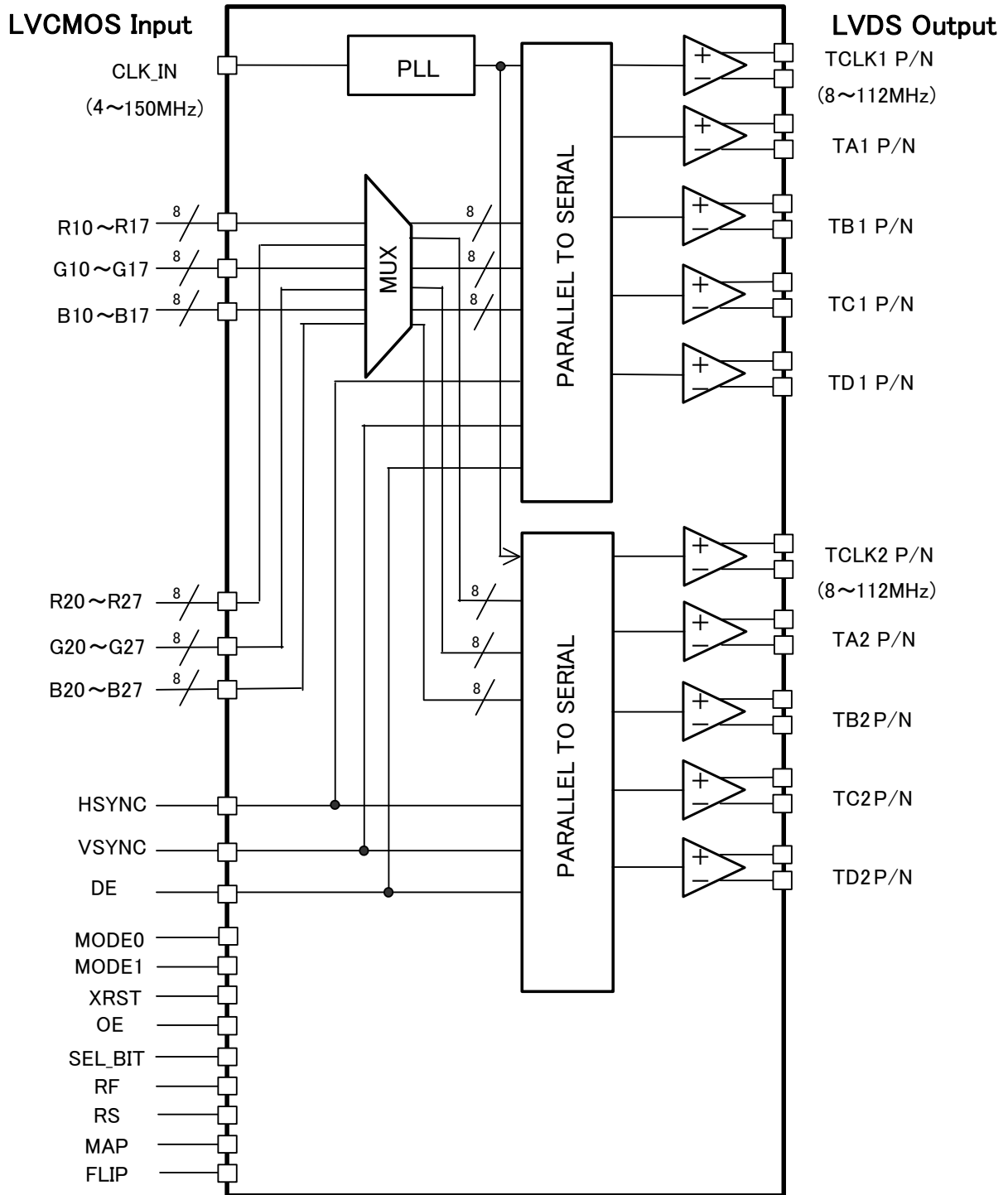


Figure-1 Block Diagram

● TQFP100V Package Outline and Specification

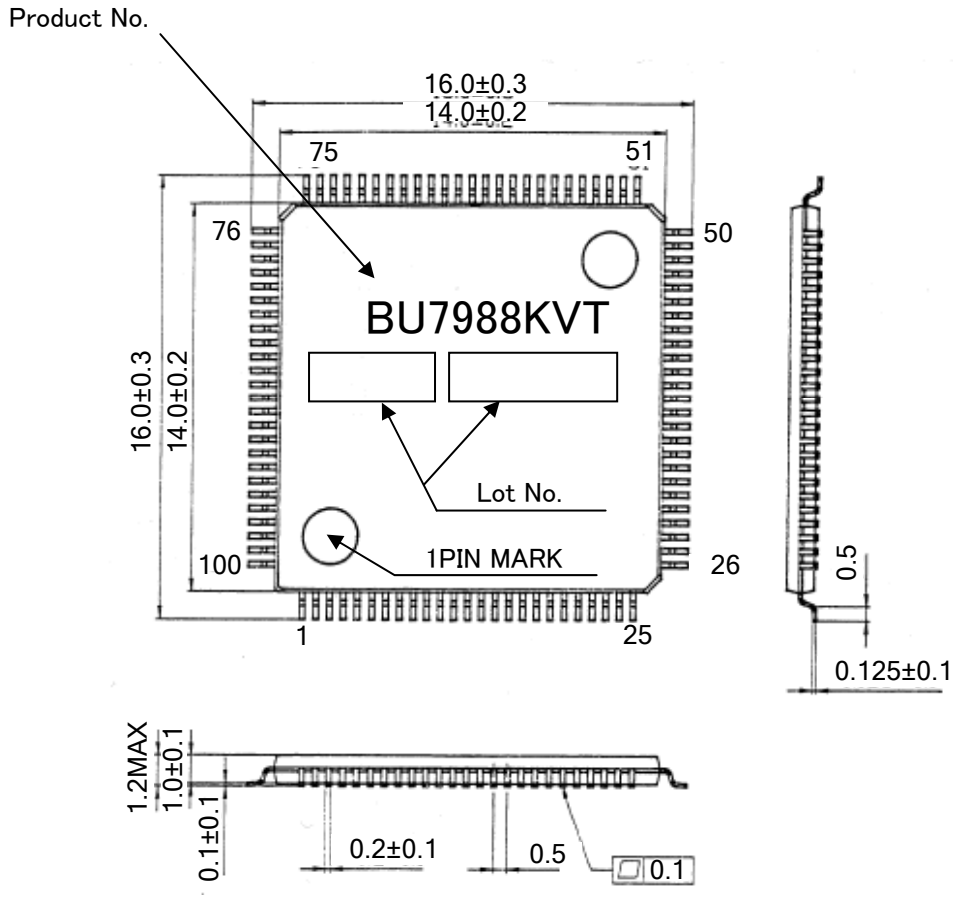


Figure-2 TQFP100V Package Outline and Specification

● Pin configuration

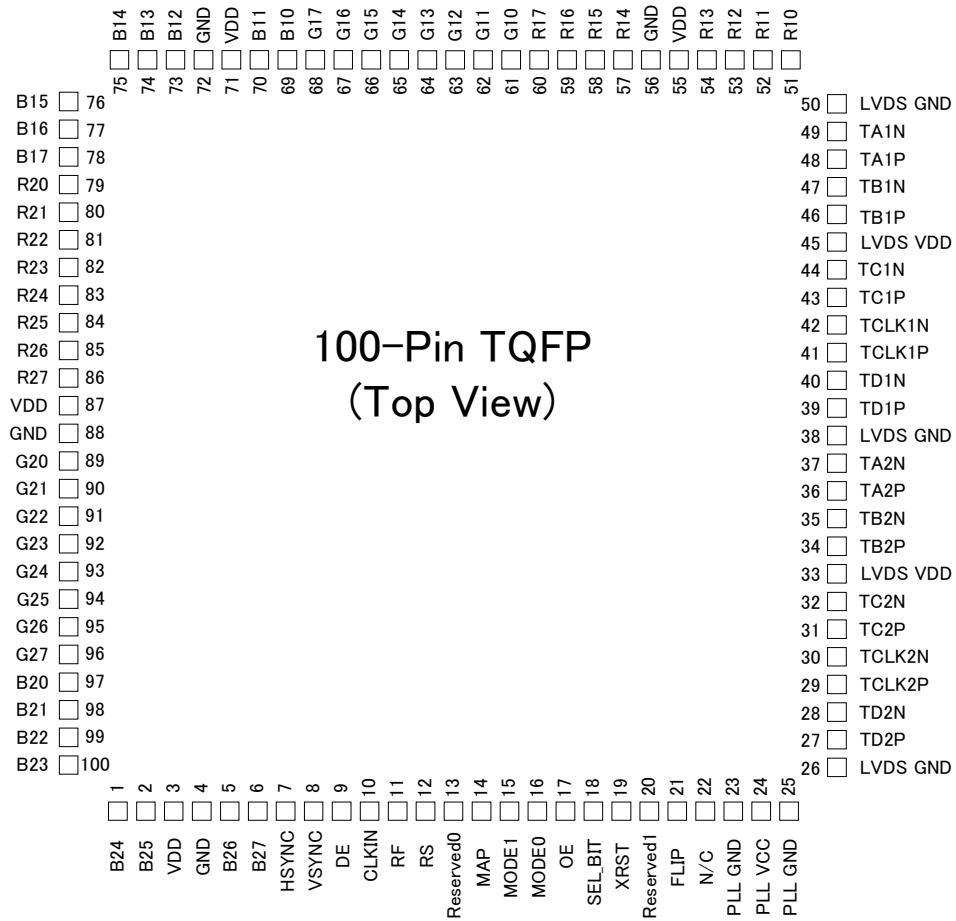


Figure-3 Pin Diagram (Top View)

● Pin Description

Table 1 : Pin Description

Pin Name	Pin No.	Type	Descriptions
TA1P, TA1N	48, 49	LVDS OUT	LVDS data out
TB1P, TB1N	46, 47	LVDS OUT	
TC1P, TC1N	43, 44	LVDS OUT	
TD1P, TD1N	39, 40	LVDS OUT	
TCLK1P, TCLK1N	41, 42	LVDS OUT	LVDS clock out
TA2P, TA2N	36, 37	LVDS OUT	LVDS data out
TB2P, TB2N	34, 35	LVDS OUT	
TC2P, TC2N	31, 32	LVDS OUT	
TD2P, TD2N	27, 28	LVDS OUT	
TCLK2P, TCLK2N	29, 30	LVDS OUT	LVDS clock out
R17~R10	60, 59, 58, 57, 54, 53, 52, 51	IN	1st Pixel data input.
G17~G10	68, 67, 66, 65, 64, 63, 62, 61	IN	
B17~B10	78, 77, 76, 75, 74, 73, 70, 69	IN	
R27~R20	86, 85, 84, 83, 82, 81, 80, 79	IN	2st Pixel data inputs.
G27~G20	96, 95, 94, 93, 92, 91, 90, 89	IN	
B27~B20	6, 5, 2, 1, 100, 99, 98, 97	IN	
DE	9	IN	DATA-ENABLE input.
VSYNC	8	IN	VSYNC input.
HSYNC	7	IN	HSYNC input.
CLKIN	10	IN	Clock Input.
MAP	14	IN	LVDS mapping table select. See Table11-14 and Figure11-14.
XRST	19	IN	H : Normal operation, L : Power down (all outputs are Hi-Z)
FLIP	21	IN	LVDS output pin select. See Table10.

Pin Name	Pin No.	Type	Descriptions															
RS	12	IN	LVDS swing mode, RS select. <table border="1"> <tr> <td>RS</td> <td>LVDS Swing</td> </tr> <tr> <td>VDD</td> <td>350mV</td> </tr> <tr> <td>GND</td> <td>200mV</td> </tr> </table>	RS	LVDS Swing	VDD	350mV	GND	200mV									
RS	LVDS Swing																	
VDD	350mV																	
GND	200mV																	
MODE1, MODE0	15, 16	IN	Pixel Data Mode <table border="1"> <tr> <th>MODE1</th> <th>MODE0</th> <th>Mode</th> </tr> <tr> <td>L</td> <td>L</td> <td>Dual-in/Dual-out</td> </tr> <tr> <td>L</td> <td>H</td> <td>Dual-in/Single-out</td> </tr> <tr> <td>H</td> <td>L</td> <td>Single-in/Dual-out</td> </tr> <tr> <td>H</td> <td>H</td> <td>Single-in/Single-out</td> </tr> </table>	MODE1	MODE0	Mode	L	L	Dual-in/Dual-out	L	H	Dual-in/Single-out	H	L	Single-in/Dual-out	H	H	Single-in/Single-out
MODE1	MODE0	Mode																
L	L	Dual-in/Dual-out																
L	H	Dual-in/Single-out																
H	L	Single-in/Dual-out																
H	H	Single-in/Single-out																
SEL_BIT	18	IN	6bit/8bit color select. H : 6bit (TDxP/N*1 are Hi-Z), L : 8bit.															
OE	17	IN	Outputs enable. H : Outputs enable, L : Output disable (all outputs are Hi-Z)															
RF	11	IN	Input Clock Triggering Select H : Rising edge, L : Falling edge															
N/C	22		Must be open															
Reserved1	20	IN	Must be tied to GND															
Reserved0	13	IN	Must be open															
VDD	3, 55, 71, 87	Power	Power Supply Pins for CMOS inputs, output and digital circuitry.															
GND	4, 56, 72, 88	Ground	Ground Pins for CMOS inputs, outputs and digital circuitry.															
LVDS VDD	33, 45	Power	Power Supply Pins for LVDS Outputs.															
LVDS GND	26, 38, 50	Ground	Ground Pins for LVDS Outputs.															
PLL VDD	24	Power	Power Supply for PLL circuitry.															
PLL GND	23, 25	Ground	Ground Pin for PLL circuitry.															

*1: X=1,2

● Electrical characteristics

■ Rating

Table 2 : Absolute Maximum Rating

Parameter	Symbol	Rating		Units
		Min	Max	
Supply Voltage	VDD	-0.3	4.0	V
Input Voltage	VIN	-0.3	VDD+0.3	V
Output Voltage	VOUT	-0.3	VDD+0.3	V
Storage Temperature Range	Tstg	-55	125	°C

Table 3 : Package Power

PACKAGE	Power Dissipation (mW)	De-rating (mW/°C)*1
TQFP100V	900	9.0
	1400*2	14.0*2

*1:At temperature Ta >25°C

*2:Package power when mounting on the PCB board.

The size of PCB board :70 × 70 × 1.6 (mm³)

The material of PCB board : The FR4 glass epoxy board.(3% or less copper foil area)

(It is recommended to apply the above package power requirement to PCB board when the small swing input mode is used)

Table 4 : Recommended Operating Conditions

Parameter	Symbol	Rating			Units	Conditions
		Min	Typ	Max		
Supply Voltage	V _{DD}	3.0	3.3	3.6	V	VDD,LVDSVDD,PLLVD
Operating Temperature Range	Topr	-20	-	85	°C	Clock frequency from 8MHz up to 90MHz
		0	-	70	°C	Clock frequency from 90MHz up to 112MHz

■ DC characteristics

Table 5 : CMOS DC Specifications (VDD=3.0V~3.6V, Ta=-20°C~+85°C)

Symbol	Parameter	Rating			Units	Conditions
		Min	Typ	Max		
V _{IH}	High Level Input Voltage	VDD × 0.8	–	VDD	V	0V ≤ V _{IN} ≤ VDD
V _{IL}	Low Level Input Voltage	GND	–	VDD × 0.2	V	
I _{INC}	Input Leak Current	-10	–	+10	μA	

Table 6 : LVDS Transmitter DC Specifications (VDD=3.0V~3.6V, Ta=-20°C~+85°C)

Symbol	Parameter	Rating			Units	Conditions	
		Min	Typ	Max		RL=100 Ω	
VOD	Differential Output Voltage	250	350	450	mV		
		120	200	300	mV	Reduced swing RS=GND	
ΔVOD	Change in VOD between complementary output states	–	–	35	mV	RL=100 Ω	
VOC	Common Mode Voltage	1.125	1.25	1.375	V		
ΔVOC	Change in VOC between complementary output states	–	–	35	mV		
I _{OS}	Output Short Circuit Current	–	–	-24	mA	V _{OUT} =0V, RL=100 Ω	
I _{OZ}	Output TRI-STATE Current	-10	–	+10	μA	XRST=0V, V _{OUT} =0V to VDD	

■ Supply Current

Table 7 : Supply Current (VDD=3.3V, Ta=25°C)

Symbol	Parameter	Rating			Units	Conditions		
		Min	Typ	Max				
I _{TCCG}	Transmitter Supply Current (Gray Scale Pattern)	-	TBD	-	mA	RS=H	MODE[1:0]=H H	f=112MHz RL=100Ω CL=5pF
		-	TBD	-			MODE[1:0]=H L	
		-	TBD	-			MODE[1:0]=L H	
		-	TBD	-			MODE[1:0]=L L	
		-	TBD	-	mA	RS=L	MODE[1:0]=H H	
		-	TBD	-			MODE[1:0]=H L	
		-	TBD	-			MODE[1:0]=L H	
		-	TBD	-			MODE[1:0]=L L	
I _{TCCW}	Transmitter Supply Current (Worst Case pattern)	-	TBD	-	mA	RS=H	MODE[1:0]=H H	f=112MHz RL=100Ω CL=5pF
		-	TBD	-			MODE[1:0]=H L	
		-	TBD	-			MODE[1:0]=L H	
		-	TBD	-			MODE[1:0]=L L	
		-	TBD	-	mA	RS=L	MODE[1:0]=H H	
		-	TBD	-			MODE[1:0]=H L	
		-	TBD	-			MODE[1:0]=L H	
		-	TBD	-			MODE[1:0]=L L	
I _{TCCS}	Transmitter Power Down Supply Current	-	-	10	μA	XRST=L		

Gray Scale Pattern

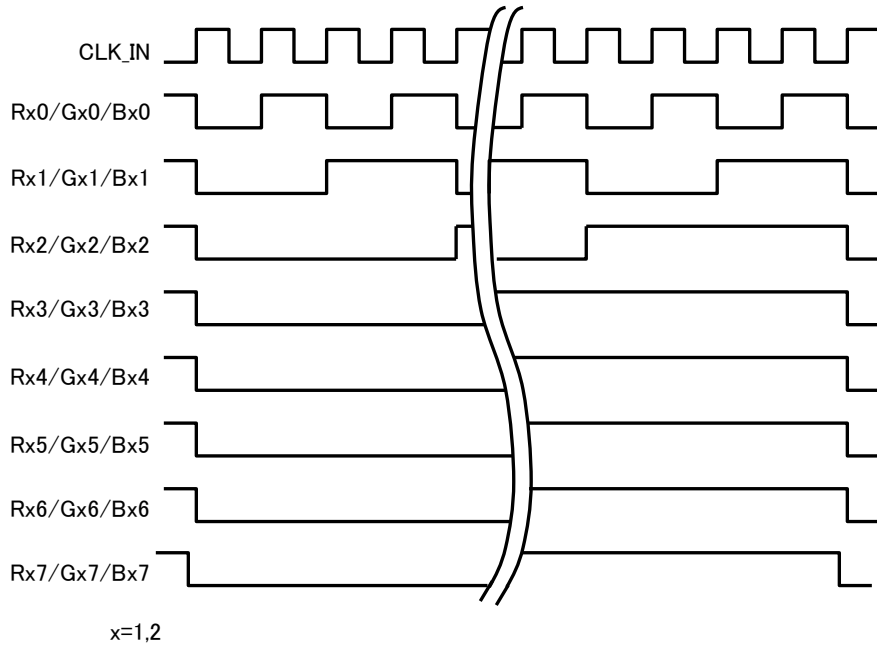


Figure-4 Gray scale pattern

Worst Case Pattern (Maximum Power condition)

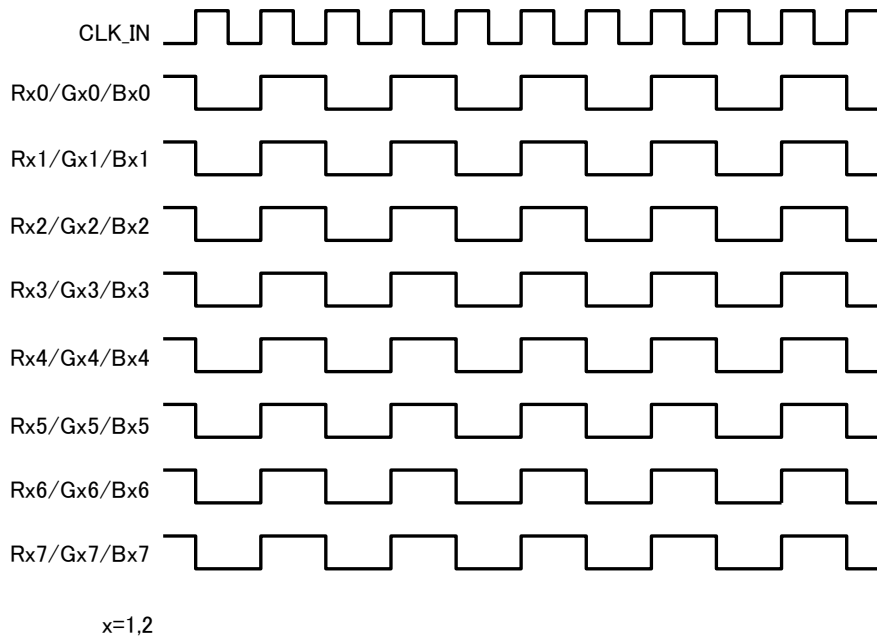


Figure-5 Worst Case Pattern

■ AC characteristics

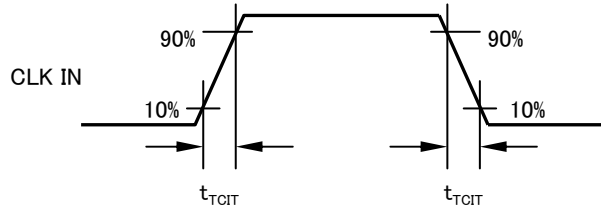
Table 8 : Switching Characteristics (VDD=3.3V, Ta=25°C)

Symbol	Parameter		Min	Typ	Max	Units
t_{TClT}	CLK IN Transition time		–	–	5.0	ns
t_{TCP}	CLK IN Period	Dual In /Dual Out	8.9	–	125.0	ns
		Dual In / Single Out	17.8	–	62.5	
		Single In / Dual Out	6.7	–	250.0	
		Single In / Single Out	8.9	–	125.0	
t_{TCH}	CLK IN High Time		$0.35t_{TCP}$	$0.5t_{TCP}$	$0.65t_{TCP}$	ns
t_{TCL}	CLK IN Low Time		$0.35t_{TCP}$	$0.5t_{TCP}$	$0.65t_{TCP}$	ns
t_{TCD}	CLK IN to TCLK+/-Delay	Dual In /Dual Out Single In/Single Out	–	TBD	–	ns
		Dual In / Single Out	–	TBD	–	
		Single In / Dual Out	–	TBD	–	
t_{TS}	CMOS Data Setup to CLK IN		2.5	–	–	ns
t_{TH}	CMOS Data Hold from CLK IN		0	–	–	ns
t_{TCOP}	CLK OUT Period	Dual In /Dual Out	8.9	–	125.0	
		Dual In / Single Out	8.9	–	125.0	
		Single In / Dual Out	13.3	–	125.0	
		Single In / Single Out	8.9	–	125.0	
t_{LVT}	LVDS Transition Time		–	0.6	1.5	ns
t_{TOP1}	Output Data Position 0		–0.2	0.0	+0.2	ns
t_{TOP0}	Output Data Position 1		$\frac{t_{TCP}}{7} - 0.2$	$\frac{t_{TCP}}{7}$	$\frac{t_{TCP}}{7} + 0.2$	ns
t_{TOP6}	Output Data Position 2		$2 \frac{t_{TCP}}{7} - 0.2$	$2 \frac{t_{TCP}}{7}$	$2 \frac{t_{TCP}}{7} + 0.2$	ns
t_{TOP5}	Output Data Position 3		$3 \frac{t_{TCP}}{7} - 0.2$	$3 \frac{t_{TCP}}{7}$	$3 \frac{t_{TCP}}{7} + 0.2$	ns
t_{TOP4}	Output Data Position 4		$4 \frac{t_{TCP}}{7} - 0.2$	$4 \frac{t_{TCP}}{7}$	$4 \frac{t_{TCP}}{7} + 0.2$	ns
t_{TOP3}	Output Data Position 5		$5 \frac{t_{TCP}}{7} - 0.2$	$5 \frac{t_{TCP}}{7}$	$5 \frac{t_{TCP}}{7} + 0.2$	ns
t_{TOP2}	Output Data Position 6		$6 \frac{t_{TCP}}{7} - 0.2$	$6 \frac{t_{TCP}}{7}$	$6 \frac{t_{TCP}}{7} + 0.2$	ns
T_{ck12}	Skew Time between TCLKXP and TCLKYP		–	–	0.5	ns
t_{PLL}	Phase Lock Loop Set Time		–	–	10.0	ms

● AC Timing

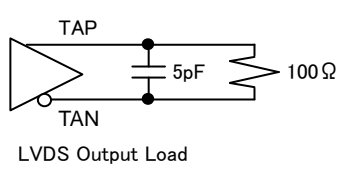
■ AC Timing Diagrams

LVCMOS Input

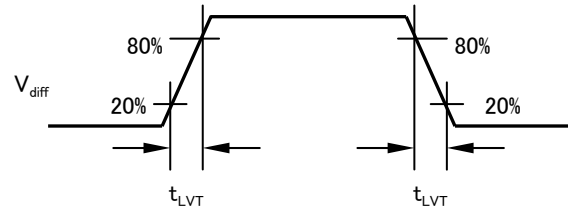


LVDS Output

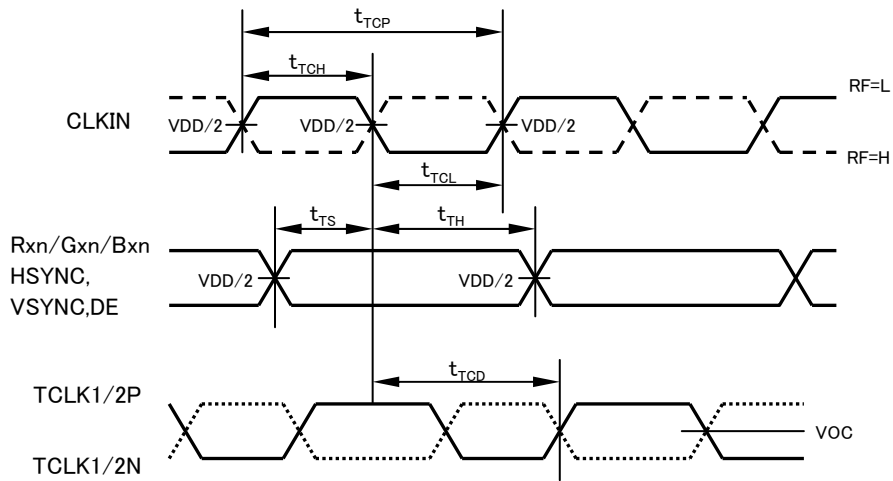
$$V_{diff} = (TAP) - (TAN)$$



LVDS Output Load



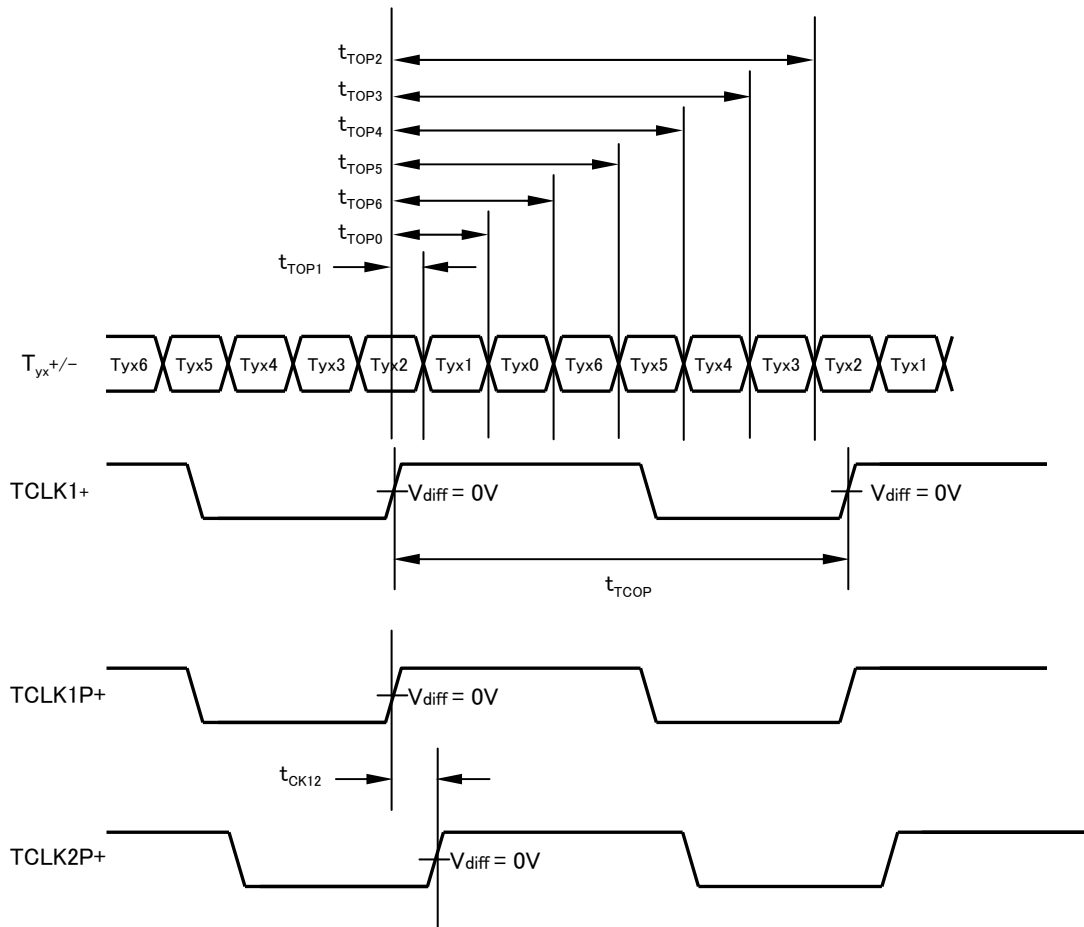
LVCMOS Input



x=1, 2
y=0-7

Figure-6 AC Timing Diagrams

■ AC Timing Diagrams



Note:
 $V_{diff} = (T_{yx+}) - (T_{yx-}), (TCLK1P) - (TCLK1N)$

Figure-7 AC Timing Diagrams

X=1,2
 Y=A,B,C,D

■ Phase Lock Loop Set Time

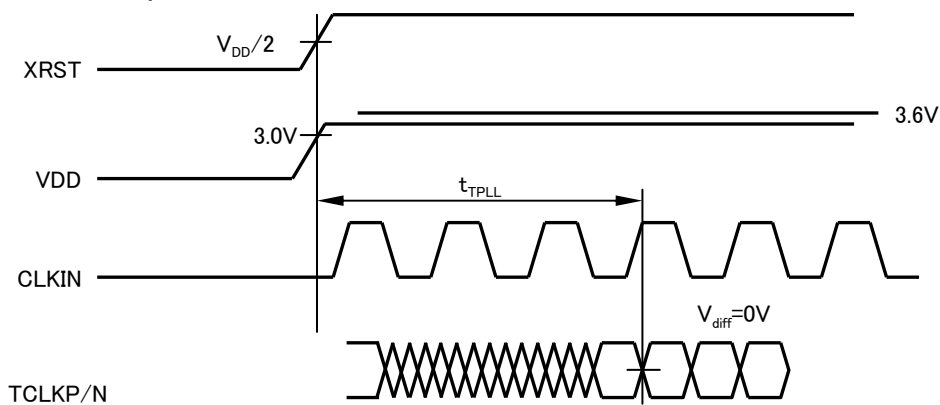


Figure-8 Phase Lock Loop Set Time

● Pixel Map Table for Dual Link

Table 9 : Pixel Map Table for Dual Link

1st Pixel Data				2nd Pixel Data			
TFT Panel Data			BU7988KVT Input	TFT Panel Data			BU7988KVT Input
	24Bit	18Bit			24Bit	18Bit	
LSB	R10	–	R10	LSB	R20	–	R20
	R11	–	R11		R21	–	R21
	R12	R10	R12		R22	R20	R22
	R13	R11	R13		R23	R21	R23
	R14	R12	R14		R24	R22	R24
	R15	R13	R15		R25	R23	R25
	R16	R14	R16		R26	R24	R26
MSB	R17	R15	R17	MSB	R27	R25	R27
LSB	G10	–	G10	LSB	G20	–	G20
	G11	–	G11		G21	–	G21
	G12	G10	G12		G22	G20	G22
	G13	G11	G13		G23	G21	G23
	G14	G12	G14		G24	G22	G24
	G15	G13	G15		G25	G23	G25
	G16	G14	G16		G26	G24	G26
MSB	G17	G15	G17	MSB	G27	G25	G27
LSB	B10	–	B10	LSB	B20	–	B20
	B11	–	B11		B21	–	B21
	B12	B10	B12		B22	B20	B22
	B13	B11	B13		B23	B21	B23
	B14	B12	B14		B24	B22	B24
	B15	B13	B15		B25	B23	B25
	B16	B14	B16		B26	B24	B26
MSB	B17	B15	B17	MSB	B27	B25	B27

● LVDS Data Output Table for Function of FLIP pin

Table 10 : LVDS Data Output Pin Name

Pin No	Output Pin Names	
	FLIP=L	FLIP=H
49	TA1N	TD2P
48	TA1P	TD2N
47	TB1N	TCLK2P
46	TB1P	TCLK2N
44	TC1N	TC2P
43	TC1P	TC2N
42	TCLK1N	TB2P
41	TCLK1P	TB2N
40	TD1N	TA2P
39	TD1P	TA2N
37	TA2N	TD1P
36	TA2P	TD1N
35	TB2N	TCLK1P
34	TB2P	TCLK1N
32	TC2N	TC1P
31	TC2P	TC1N
30	TCLK2N	TB1P
29	TCLK2P	TB1N
28	TD2N	TA1P
27	TD2P	TA1N

● LVC MOS Data Input Timing for Dual Link

Example : SXGA+(1400 × 1050)

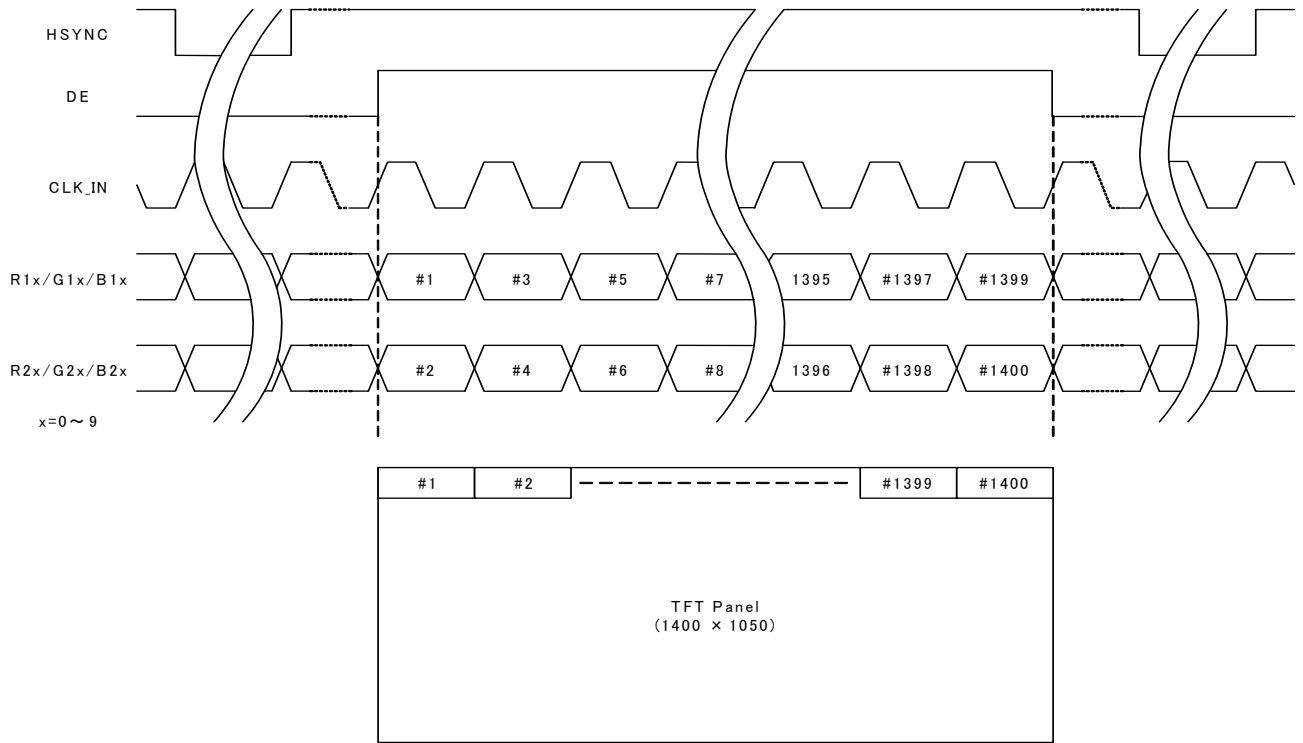


Figure-9 LVC MOS Data Input Timing for Dual Link

● LVC MOS Data Input Timing for Single Link

Example : SXGA+(1400 × 1050)

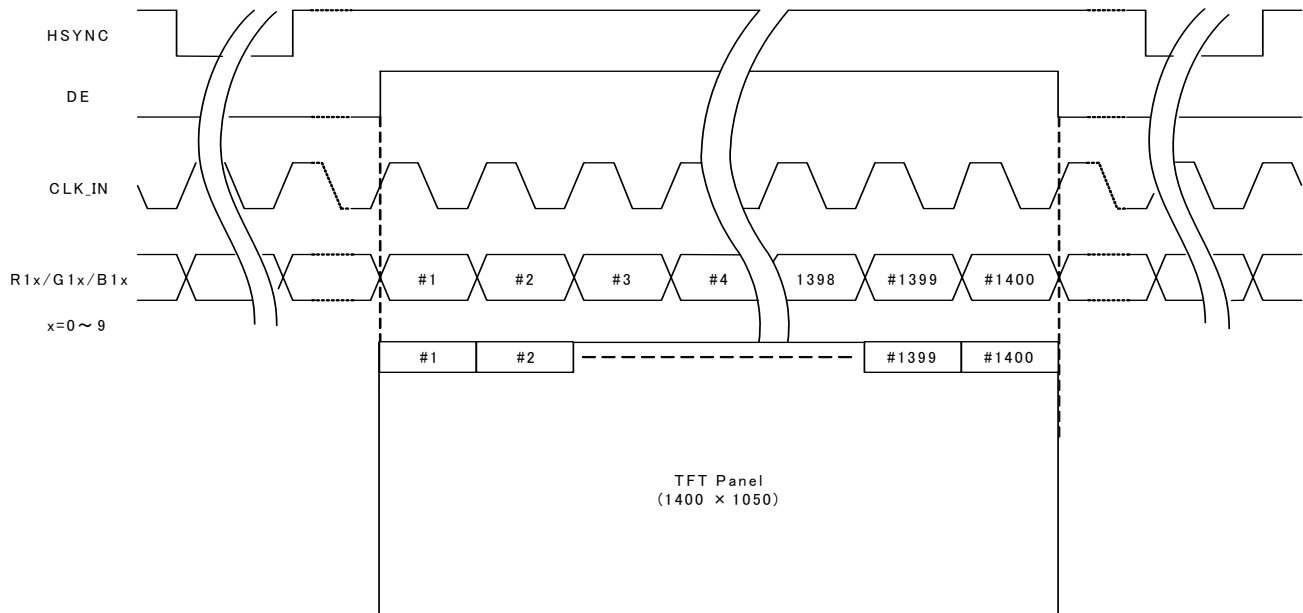
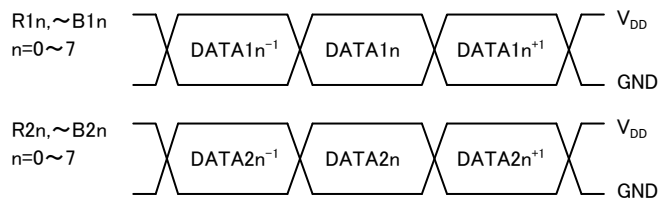
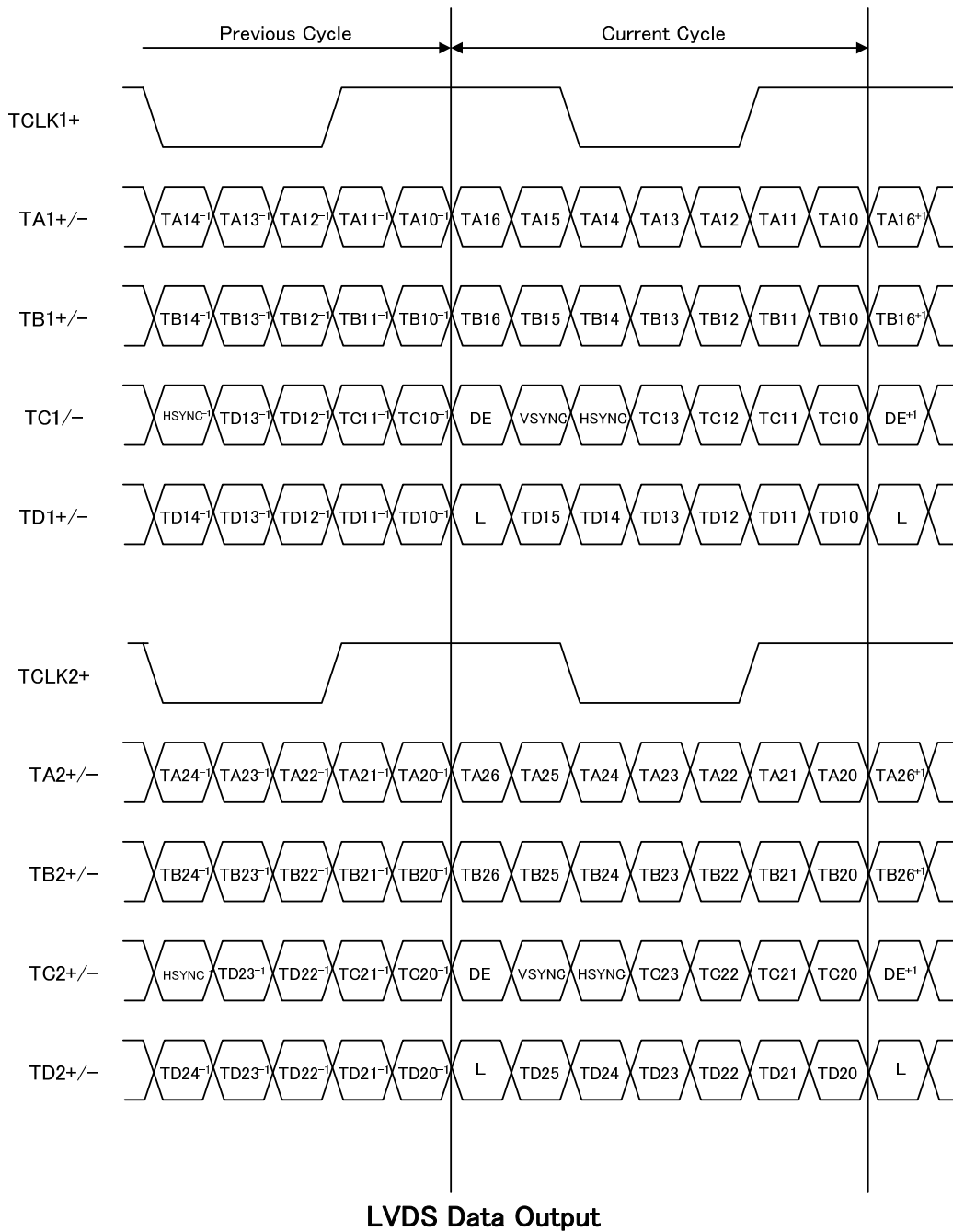


Figure-10 LVC MOS Data Input Timing for Single Link

● LVDS Output Data Mapping (Dual Link / Single Link)



LVC MOS Data Input

Figure-11 LVDS Output Data Mapping

● LVCMOS Data Inputs Timing in Dual Link

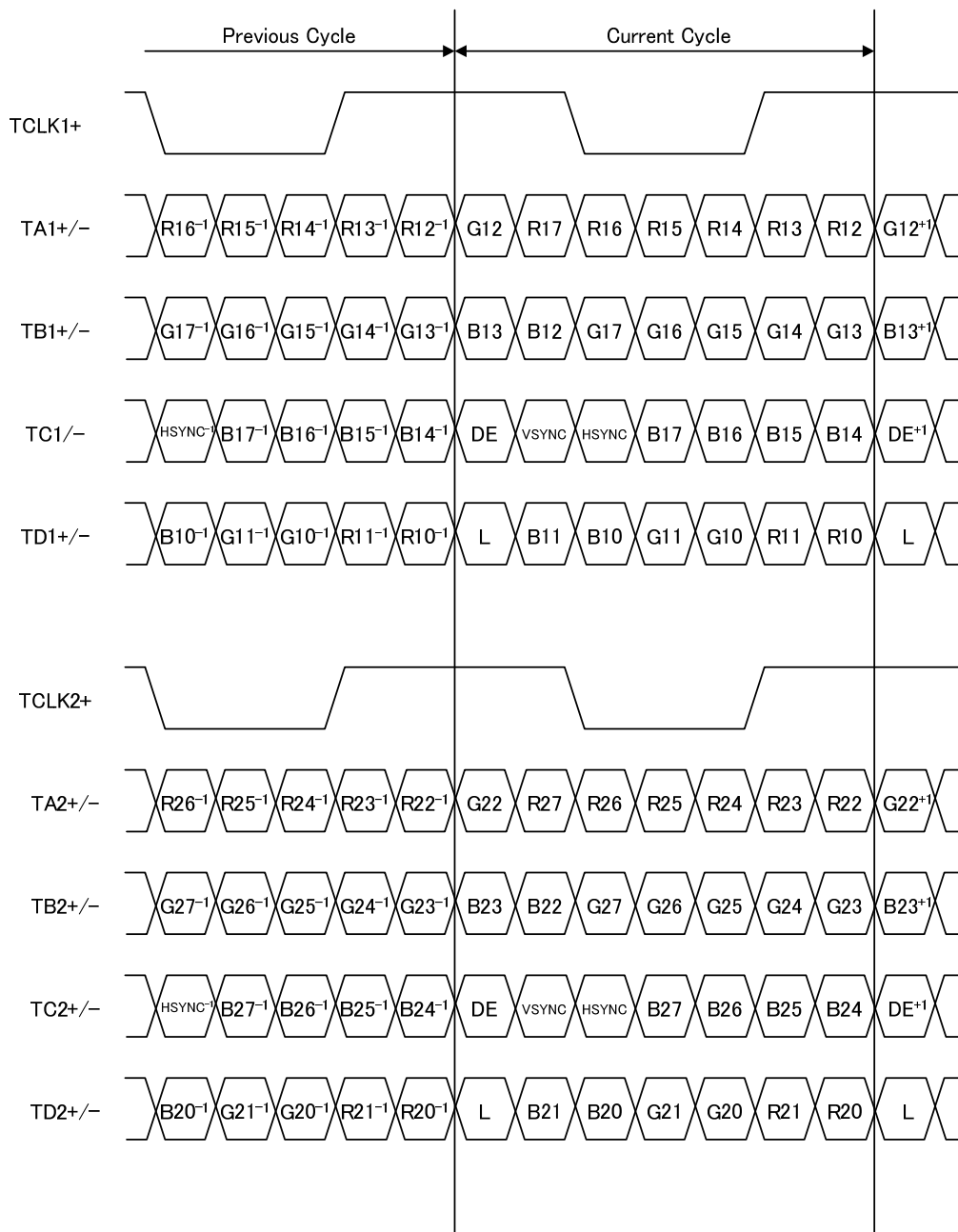
Dual-in / Dual-out Mode (MODE<1:0>=LL , FLIP=L)

Table 11 : LVCMOS Data Inputs Timing Diagrams in Dual Link

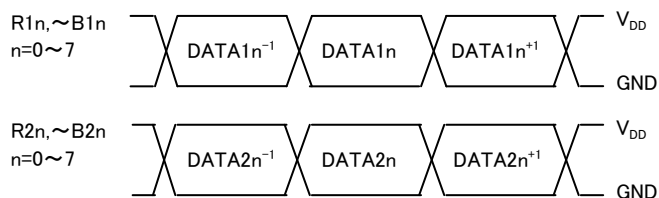
1st Pixel Data			2nd Pixel Data		
LVDS Output Data (1st Pixel Data)	MAP=H Input Pin Name	MAP=L Input Pin Name	LVDS Output Data (2nd Pixel Data)	MAP=H Input Pin Name	MAP=L Input Pin Name
TA10	R12	R10	TA20	R22	R20
TA11	R13	R11	TA21	R23	R21
TA12	R14	R12	TA22	R24	R22
TA13	R15	R13	TA23	R25	R23
TA14	R16	R14	TA24	R26	R24
TA15	R17	R15	TA25	R27	R25
TA16	G12	G10	TA26	G22	G20
TB10	G13	G11	TB20	G23	G21
TB11	G14	G12	TB21	G24	G22
TB12	G15	G13	TB22	G25	G23
TB13	G16	G14	TB23	G26	G24
TB14	G17	G15	TB24	G27	G25
TB15	B12	B10	TB25	B22	B20
TB16	B13	B11	TB26	B23	B21
TC10	B14	B12	TC20	B24	B22
TC11	B15	B13	TC21	B25	B23
TC12	B16	B14	TC22	B26	B24
TC13	B17	B15	TC23	B27	B25
TC14	HSYNC	HSYNC	TC24	HSYNC	HSYNC
TC15	VSYNC	VSYNC	TC25	VSYNC	VSYNC
TC16	DE	DE	TC26	DE	DE
TD10	R10	R16	TD20	R20	R26
TD11	R11	R17	TD21	R21	R27
TD12	G10	G16	TD22	G20	G26
TD13	G11	G17	TD23	G21	G27
TD14	B10	B16	TD24	B20	B26
TD15	B11	B17	TD25	B21	B27
TD16	L	L	TD26	L	L

● LVC MOS Data Inputs Timing Diagrams in Dual Link

Dual-in / Dual-out Mode (MODE<1:0>=LL, FLIP=L, MAP=H)



LVDS Data Output



LVC MOS Data Input

Figure-12 LVC MOS Data Inputs Timing Diagrams in Dual Link

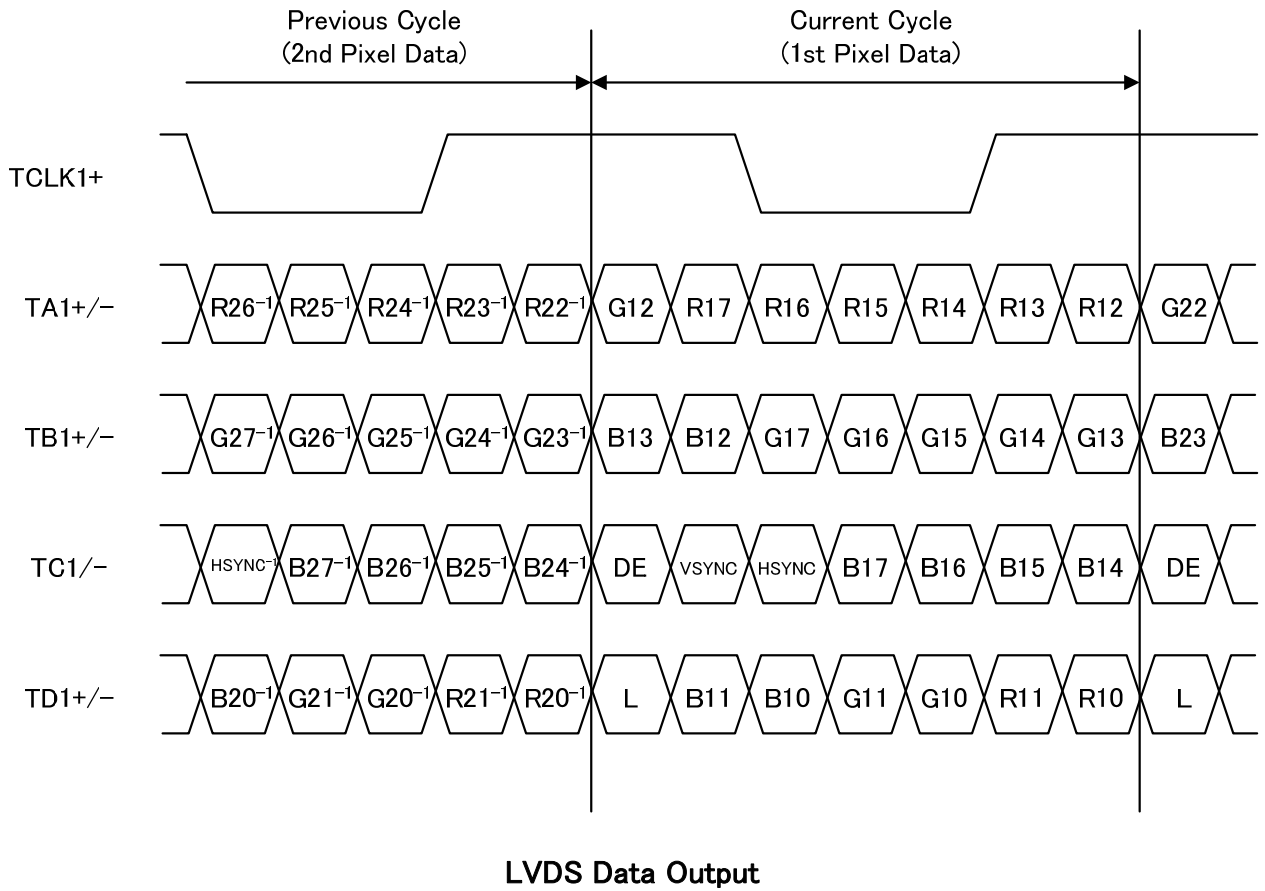
● LVCMOS Data Inputs Timing in Single Link

Dual-in / Single-out Mode (MODE<1:0>=LH, FLIP=L)

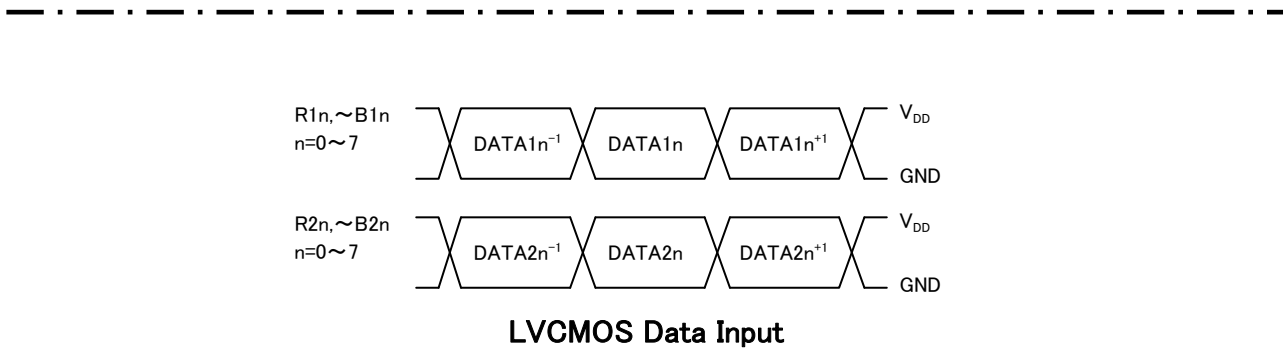
Table 12 : LVCMOS Data Inputs Timing Diagrams in Dual Link

LVDS Output Data (1st Pixel Data)	Mapping Mode1 (Input Pin Name)	Mapping Mode2 (Input Pin Name)
TA10	R12/R22	R10/R20
TA11	R13/R23	R11/R21
TA12	R14/R24	R12/R22
TA13	R15/R25	R13/R23
TA14	R16/R26	R14/R24
TA15	R17/R27	R15/R25
TA16	G12/G22	G10/G20
TB10	G13/G23	G11/G21
TB11	G14/G24	G12/G22
TB12	G15/G25	G13/G23
TB13	G16/G26	G14/G24
TB14	G17/G27	G15/G25
TB15	B12/B22	B10/B20
TB16	B13/B23	B11/B21
TC10	B14/B24	B12/B22
TC11	B15/B25	B13/B23
TC12	B16/B26	B14/B24
TC13	B17/B27	B15/B25
TC14	HSYNC	HSYNC
TC15	VSYNC	VSYNC
TC16	DE	DE
TD10	R10/R20	R16/R26
TD11	R11/R21	R17/R27
TD12	G10/G20	G16/G26
TD13	G11/G21	G17/G27
TD14	B10/B20	B16/B26
TD15	B11/B21	B17/B27
TD16	L	L

● LVC MOS Data Inputs Timing Diagrams in Single Link
 Dual-in / Single-out Mode (MODE<1:0>=LH, FLIP=L, MAP=H)



LVDS Data Output



LVC MOS Data Input

Figure-13 LVC MOS Data Inputs Timing Diagrams in Single Link

● LVCMOS Data Inputs Timing in Single Link

Single-in / Dual-out Mode (MODE<1:0>=HH, FLIP=L)

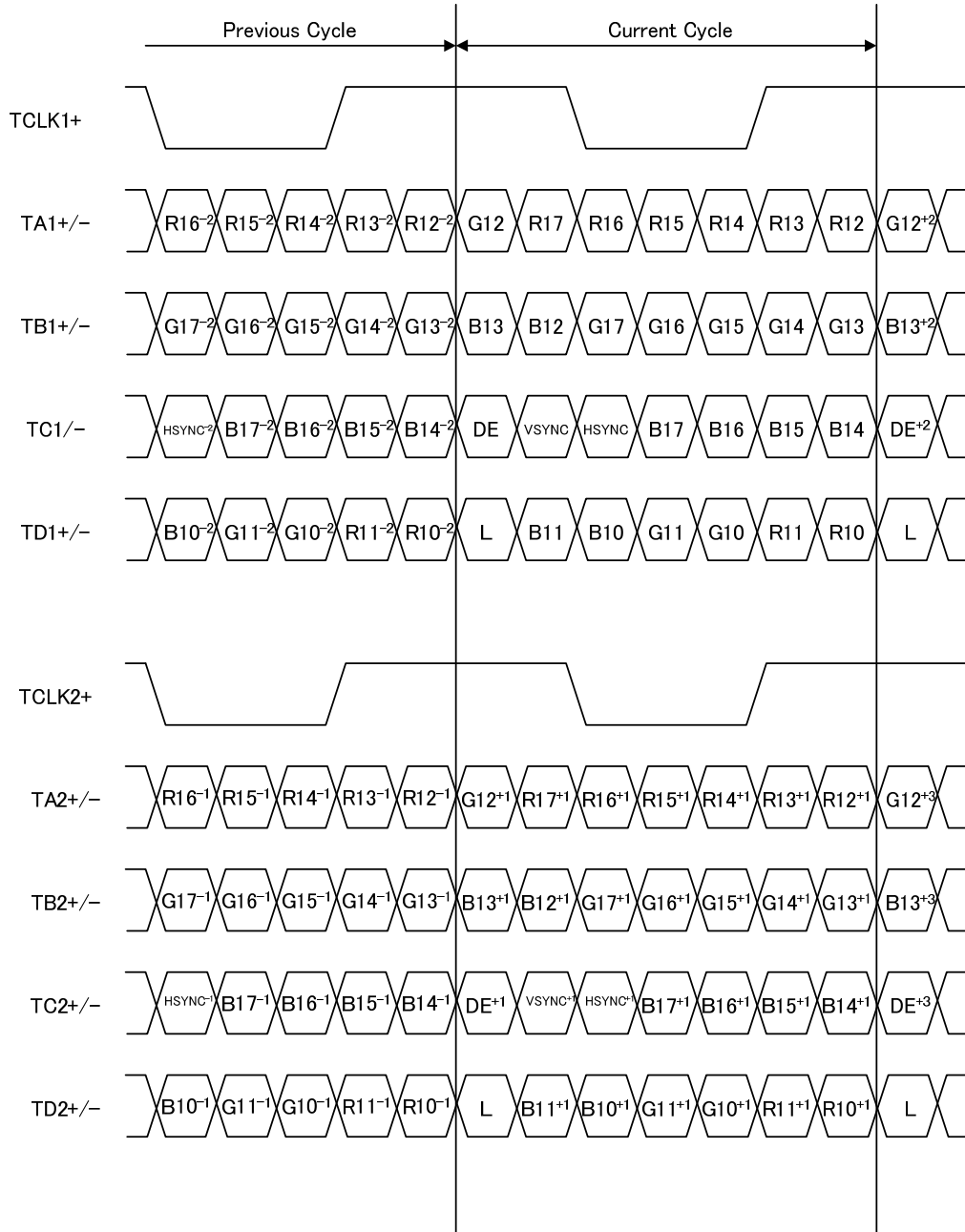
Table 13 : LVCMOS Data Inputs Timing Diagrams in Single Link

1st Pixel Data			2nd Pixel Data		
LVDS Output Data (1st Pixel Data)	MAP=H Input Pin Name	MAP=L Input Pin Name	LVDS Output Data (1st Pixel Data)	MAP=H Input Pin Name	MAP=L Input Pin Name
TA10	R12	R10	TA20	R12 ⁺¹	R10 ⁺¹
TA11	R13	R11	TA21	R13 ⁺¹	R11 ⁺¹
TA12	R14	R12	TA22	R14 ⁺¹	R12 ⁺¹
TA13	R15	R13	TA23	R15 ⁺¹	R13 ⁺¹
TA14	R16	R14	TA24	R16 ⁺¹	R14 ⁺¹
TA15	R17	R15	TA25	R17 ⁺¹	R15 ⁺¹
TA16	G12	G10	TA26	G12 ⁺¹	G10 ⁺¹
TB10	G13	G11	TB20	G13 ⁺¹	G11 ⁺¹
TB11	G14	G12	TB21	G14 ⁺¹	G12 ⁺¹
TB12	G15	G13	TB22	G15 ⁺¹	G13 ⁺¹
TB13	G16	G14	TB23	G16 ⁺¹	G14 ⁺¹
TB14	G17	G15	TB24	G17 ⁺¹	G15 ⁺¹
TB15	B12	B10	TB25	B12 ⁺¹	B10 ⁺¹
TB16	B13	B11	TB26	B13 ⁺¹	B11 ⁺¹
TC10	B14	B12	TC20	B14 ⁺¹	B12 ⁺¹
TC11	B15	B13	TC21	B15 ⁺¹	B13 ⁺¹
TC12	B16	B14	TC22	B16 ⁺¹	B14 ⁺¹
TC13	B17	B15	TC23	B17 ⁺¹	B15 ⁺¹
TC14	HSYNC	HSYNC	TC24	HSYNC ⁺¹	HSYNC ⁺¹
TC15	VSYNC	VSYNC	TC25	VSYNC ⁺¹	VSYNC ⁺¹
TC16	DE	DE	TC26	DE ⁺¹	DE ⁺¹
TD10	R10	R16	TD20	R10 ⁺¹	R16 ⁺¹
TD11	R11	R17	TD21	R11 ⁺¹	R17 ⁺¹
TD12	G10	G16	TD22	G10 ⁺¹	G16 ⁺¹
TD13	G11	G17	TD23	G11 ⁺¹	G17 ⁺¹
TD14	B10	B16	TD24	B10 ⁺¹	B16 ⁺¹
TD15	B11	B17	TD25	B11 ⁺¹	B17 ⁺¹
TD16	L	L	TD26	L	L

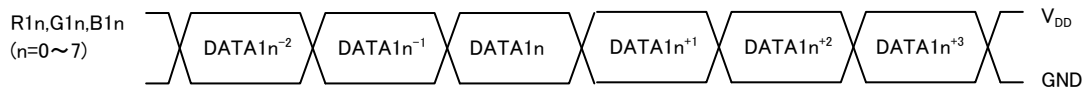
● LVC MOS Data Inputs Timing in Dual Link

Single-in / Dual-out Mode

(MODE<1:0>=HL, FLIP=L, MAP=H)



LVDS Data Output



LVC MOS Data Input

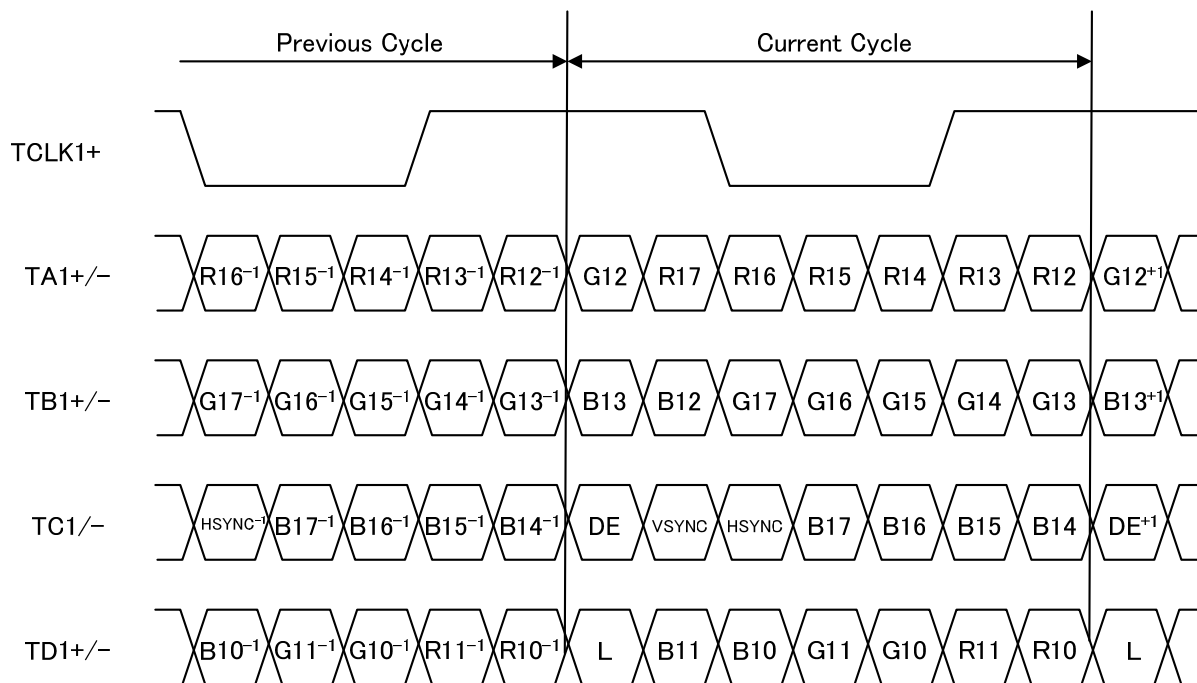
Figure-14 LVC MOS Data Inputs Timing in Dual Link

● LVC MOS Data Inputs Timing in Single Link
 Single-in / Single-out Mode (MODE<1:0>=HH, FLIP=L)

Table 14 : LVC MOS Data Inputs Timing Diagrams in Single Link

LVDS Output Data (1st Pixel Data)	MAP=H Input Pin Name	MAP=L Input Pin Name
TA10	R12	R10
TA11	R13	R11
TA12	R14	R12
TA13	R15	R13
TA14	R16	R14
TA15	R17	R15
TA16	G12	G10
TB10	G13	G11
TB11	G14	G12
TB12	G15	G13
TB13	G16	G14
TB14	G17	G15
TB15	B12	B10
TB16	B13	B11
TC10	B14	B12
TC11	B15	B13
TC12	B16	B14
TC13	B17	B15
TC14	HSYNC	HSYNC
TC15	VSYNC	VSYNC
TC16	DE	DE
TD10	R10	R16
TD11	R11	R17
TD12	G10	G16
TD13	G11	G17
TD14	B10	B16
TD15	B11	B17
TD16	L	L

● LVC MOS Data Inputs Timing Diagrams in Single Link
 Single-in / Single-out Mode (MODE<1:0>=HH, FLIP=L, MAP=H)



LVDS Data Output



LVC MOS Data Input

Figure-15 LVC MOS Data Inputs Timing Diagrams in Single Link

● About the Power On Reset

Power On Reset is not mandatory for this device.

(The PD pin should be set to high level when Power On Reset procedure is not used.)

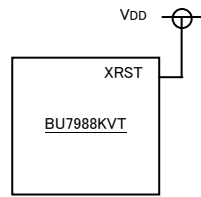


Figure-16 terminal connection when Power On Reset is not used

However, Power On Reset procedure is strongly recommend for internal logic initialization by following two methods.

- ① The method of using CR circuit.
- ② The method of using external specific IC.

It is recommend to do enough examination for target application.

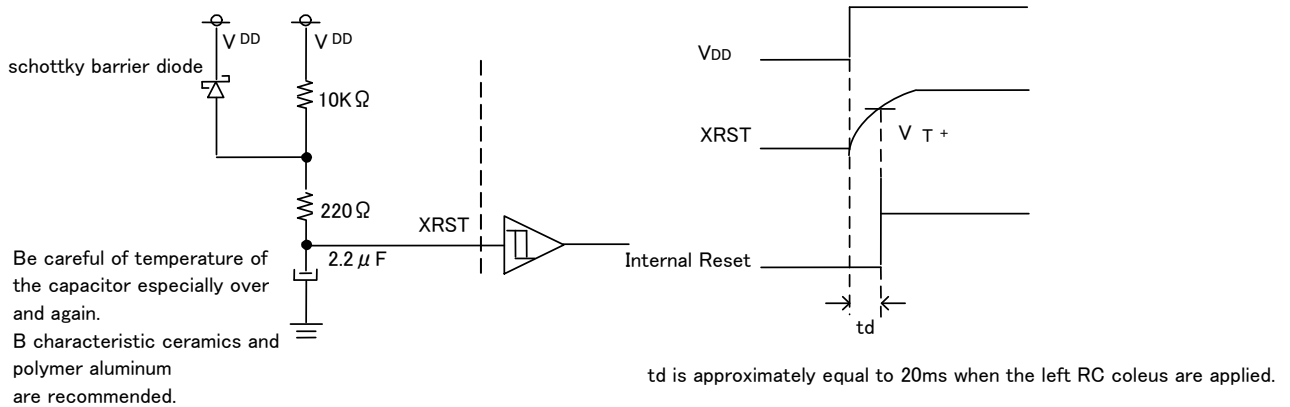


Figure-17 Power On Reset by external a CR circuit

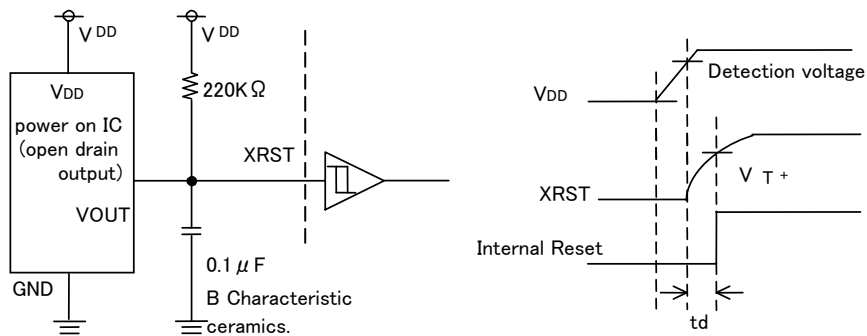
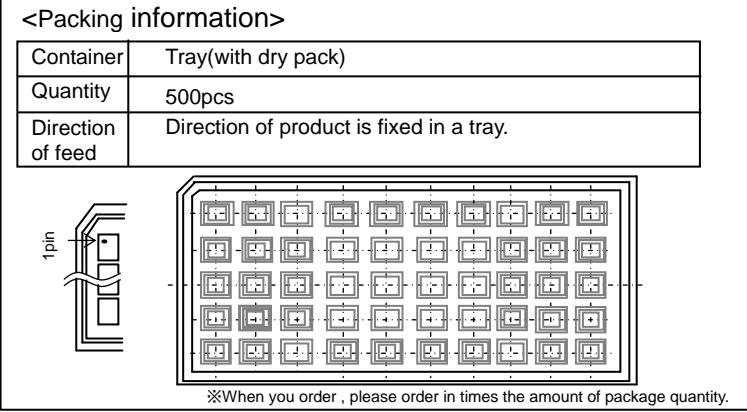
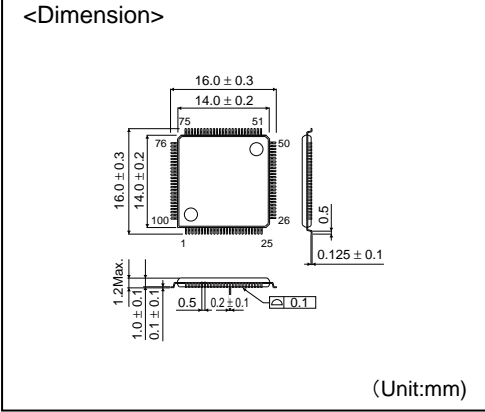


Figure-18 Power On Reset by specific IC

TQFP100V



- The contents described herein are correct as of June, 2008
- The contents described herein are subject to change without notice. For updates of the latest information, please contact and confirm with ROHM CO.,LTD.
- Any part of this application note must not be duplicated or copied without our permission.
- Application circuit diagrams and circuit constants contained herein are shown as examples of standard use and operation. Please pay careful attention to the peripheral conditions when designing circuits and deciding upon circuit constants in the set.
- Any data, including, but not limited to application circuit diagrams and information, described herein are intended only as illustrations of such devices and not as the specifications for such devices. ROHM CO.,LTD. disclaims any warranty that any use of such devices shall be free from infringement of any third party's intellectual property rights or other proprietary rights, and further, assumes no liability of whatsoever nature in the event of any such infringement, or arising from or connected with or related to the use of such devices.
- Upon the sale of any such devices, other than for buyer's right to use such devices itself, resale or otherwise dispose of the same, implied right or license to practice or commercially exploit any intellectual property rights or other proprietary rights owned or controlled by ROHM CO., LTD. is granted to any such buyer.
- The products described herein utilize silicon as the main material.
- The products described herein are not designed to be X ray proof.

The products listed in this catalog are designed to be used with ordinary electronic equipment or devices (such as audio visual equipment, office-automation equipment, communications devices, electrical appliances and electronic toys). Should you intend to use these products with equipment or devices which require an extremely high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), please be sure to consult with our sales representative in advance.

Contact us for further information about the products.

Excellence in Electronics

ROHM CO., LTD.

21, Saiin Mizosaki-cho, Ukyo-ku, Kyoto
615-8585, Japan
TEL: +81-75-311-2121 FAX: +81-75-315-0172
URL: <http://www.rohm.com>

Published by
LSI Business Promotion Dept.

San Diego TEL: +1-858-625-3630 FAX: +1-858-625-3670
Atlanta TEL: +1-770-754-5972 FAX: +1-770-754-0691
Boston TEL: +1-978-371-0382 FAX: +1-928-438-7164
Chicago TEL: +1-847-368-1006 FAX: +1-847-368-1008
Dallas TEL: +1-469-287-5366 FAX: +1-469-362-7973
Denver TEL: +1-303-708-0908 FAX: +1-303-708-0858
Detroit TEL: +1-248-348-9920 FAX: +1-248-348-9942
Nashville TEL: +1-615-620-6700 FAX: +1-615-620-6702
Mexico TEL: +52-33-3123-2001 FAX: +52-33-3123-2002
Düsseldorf TEL: +49-2154-9210 FAX: +49-2154-921400
Munich TEL: +49-8161-48310 FAX: +49-8161-483120
Stuttgart TEL: +49-711-72723710 FAX: +49-711-72723720
France TEL: +33-1-5697-3060 FAX: +33-1-5697-3080
United Kingdom TEL: +44-1-908-306700 FAX: +44-1-908-235788
Denmark TEL: +45-3694-4739 FAX: +45-3694-4789
Barcelona TEL: +34-9375-24320 FAX: +34-9375-24410
Hungary TEL: +36-1-4719338 FAX: +36-1-4719339
Poland TEL: +48-22-5757213 FAX: +48-22-5757001
Russia TEL: +7-95-980-6755 FAX: +7-95-937-8290
Seoul TEL: +82-2-8182-700 FAX: +82-2-8182-715
Masan TEL: +82-55-240-6234 FAX: +82-55-240-6236
Dalian TEL: +86-411-8230-8549 FAX: +86-411-8230-8537
Beijing TEL: +86-10-8525-2483 FAX: +86-10-8525-2489
Tianjin TEL: +86-22-23029181 FAX: +86-22-23029183

Shanghai TEL: +86-21-6279-2727 FAX: +86-21-6247-2066
Hangzhou TEL: +86-571-87658072 FAX: +86-571-87658071
Nanjing TEL: +86-25-8689-0015 FAX: +86-25-8689-0393
Ningbo TEL: +86-574-87654201 FAX: +86-574-87654208
Qingdao TEL: +86-532-5779-312 FAX: +86-532-5779-653
Suzhou TEL: +86-512-6807-1300 FAX: +86-512-6807-2300
Wuxi TEL: +86-510-82702693 FAX: +86-510-82702992
Shenzhen TEL: +86-755-8307-3008 FAX: +86-755-8307-3003
Dongguan TEL: +86-769-8393-3320 FAX: +86-769-8398-4140
Fuzhou TEL: +86-591-8801-8698 FAX: +86-591-8801-8690
Guangzhou TEL: +86-20-8364-9796 FAX: +86-20-8364-9707
Huizhou TEL: +86-752-205-1054 FAX: +86-752-205-1059
Xiamen TEL: +86-592-238-5705 FAX: +86-592-239-8380
Zhuhai TEL: +86-756-3232-480 FAX: +86-756-3232-460
Hong Kong TEL: +852-2-740-6262 FAX: +852-2-375-8971
Taipei TEL: +886-7-237-0881 FAX: +886-7-237-0881
Kaohsiung TEL: +886-7-237-0881 FAX: +886-7-238-7332
Singapore TEL: +65-6332-2322 FAX: +65-6332-5662
Philippines TEL: +63-2-807-6872 FAX: +63-2-809-1422
Thailand TEL: +66-2-254-4890 FAX: +66-2-256-6334
Kuala Lumpur TEL: +60-3-7958-8355 FAX: +60-3-7958-8377
Penang TEL: +60-4-2286453 FAX: +60-4-2286452
Kyoto TEL: +81-75-365-1218 FAX: +81-75-365-1228
Yokohama TEL: +81-45-476-2290 FAX: +81-45-476-2295